

<b>Notice of References Cited</b>		Application/Control No. 10/825,103	Applicant(s)/Patent Under Reexamination SAITO ET AL.	
		Examiner Craig A. Renner	Art Unit 2627	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Mechanical Packaging Scheme With Considerations for Maximum ESD/EMC Protection, Efficient Cooling And Quiet Office Environment," IBM Technical Disclosure Bulletin, Vol. 33, Iss. 9, Pages 379-383, February 1, 1991.
	V	Machine Translation of JP 2001-125667, published May 11, 2001 to Fujihata et al.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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